Octal D-Type Flip-Flop with 3-State Output

The MC74VHCT374A is an advanced high speed CMOS octal flip-flop with 3-state output fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

This 8-bit D-type flip-flop is controlled by a clock input and an output enable input. When the output enable input is high, the eight outputs are in a high impedance state.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output.

The VHCT inputs are compatible with TTL levels. This device can be used as a level converter for interfacing 3.3 V to 5.0 V, because it has full 5.0 V CMOS level output swings.

The VHCT374A input and output (when disabled) structures provide protection when voltages between 0 V and 5.5 V are applied, regardless of the supply voltage. These input and output structures help prevent device destruction caused by supply voltage—input/output voltage mismatch, battery backup, hot insertion, etc.

Features

- High Speed: $f_{max} = 140 \text{ MHz}$ (Typ) at $V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 4 \mu A$ (Max) at $T_A = 25^{\circ}C$
- TTL-Compatible Inputs: $V_{IL} = 0.8 \text{ V}$; $V_{IH} = 2.0 \text{ V}$
- Power Down Protection Provided on Inputs and Outputs
- Balanced Propagation Delays
- Designed for 4.5 V to 5.5 V Operating Range
- Low Noise: $V_{OLP} = 1.6 \text{ V (Max)}$
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance:

Human Body Model > 2000 V; Machine Model > 200 V

- Chip Complexity: 276 FETs or 69 Equivalent Gates
- These Devices are Pb-Free and are RoHS Compliant

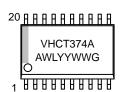


ON Semiconductor®

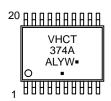
http://onsemi.com

MARKING DIAGRAMS









A = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G or • = Pb-Free Package

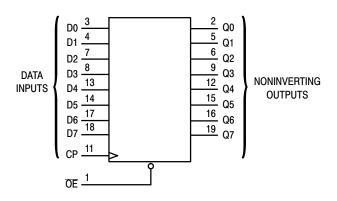
(Note: Microdot may be in either location)

FUNCTION TABLE

	INPUTS	OUTPUT	
ŌĒ	СР	D	q
L L L		H L X	H L No Change Z

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.





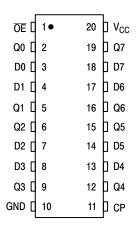


Figure 2. Pin Assignment

MAXIMUM RATINGS

Symbol	Paramete	7	Value	Unit
V _{CC}	DC Supply Voltage	DC Supply Voltage		
V _{in}	DC Input Voltage		- 0.5 to + 7.0	V
V _{out}	DC Output Voltage	Outputs in 3–State High or Low State	- 0.5 to + 7.0 - 0.5 to V _{CC} + 0.5	V
I _{IK}	Input Diode Current		- 20	mA
lok	Output Diode Current (V _{OUT} < 0	± 20	mA	
l _{out}	DC Output Current, per Pin		± 25	mA
Icc	DC Supply Current, V _{CC} and G	ND Pins	± 75	mA
P _D	Power Dissipation in Still Air,	SOIC Package† TSSOP Package†	500 450	mW
T _{stg}	Storage Temperature		- 65 to + 150	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND \leq (V_{in} or V_{out}) \leq V_{CC} .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

†Derating – SOIC Packages: – 7 mW/°C from 65° to 125°C TSSOP Package: – 6.1 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage	4.5	5.5	V
V _{in}	DC Input Voltage	0	5.5	V
V _{out}	DC Output Voltage Outputs in 3–State High or Low State	0	5.5 V _{CC}	V
T _A	Operating Temperature	- 40	+ 85	°C
t _r , t _f	Input Rise and Fall Time V _{CC} =5.0V ±0.5V	0	20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

			V _{CC}		T _A = 25	°C	T _A = - 40	0 to 85°C	
Symbol	Parameter	Test Conditions	v	Min	Тур	Max	Min	Max	Unit
V _{IH}	Minimum High-Level Input Voltage		4.5 to 5.5	2.0			2.0		V
V _{IL}	Maximum Low-Level Input Voltage		4.5 to 5.5			0.8		0.8	V
V _{OH}	Minimum High-Level Output	I _{OH} = - 50μA	4.5	4.4	4.5		4.4		V
	Voltage $V_{in} = V_{IH}$ or V_{IL}	I _{OH} = - 8mA	4.5	3.94			3.80		
V _{OL}	Maximum Low-Level Output	I _{OL} = 50μA	4.5		0.0	0.1		0.1	V
	Voltage $V_{in} = V_{IH}$ or V_{IL}	I _{OL} = 8mA	4.5			0.36		0.44	
l _{in}	Maximum Input Leakage Current	V _{in} = 5.5 V or GND	0 to 5.5			± 0.1		± 1.0	μΑ
I _{OZ}	Maximum 3–State Leakage Current	$V_{in} = V_{IL} \text{ or } V_{IH}$ $V_{out} = V_{CC} \text{ or GND}$	5.5			± 0.25		± 2.5	μА
I _{CC}	Maximum Quiescent Supply Current	V _{in} = V _{CC} or GND	5.5			4.0		40.0	μΑ
I _{CCT}	Quiescent Supply Current	Per Input: V _{IN} = 3.4V Other Input: V _{CC} or GND	5.5			1.35		1.50	mA
I _{OPD}	Output Leakage Current	V _{OUT} = 5.5V	0			0.5		5.0	μΑ

AC ELECTRICAL CHARACTERISTICS (Input $t_f = t_f = 3.0 \text{ns}$)

				T _A = 25	°C	$T_A = -40$	to 85°C	
Symbol	Parameter	Test Conditions	Min	Тур	Max	Min	Max	Unit
f _{max}	Maximum Clock Frequency (50% Duty Cycle)	$V_{CC} = 5.0 \pm 0.5 V$ $C_L = 15 pF$ $C_L = 50 pF$	90 85	140 130		80 95		MHz
t _{PLH} , t _{PHL}	Maximum Propagation Delay, CP to Q	$V_{CC} = 5.0 \pm 0.5 V$ $C_L = 15 pF$ $C_L = 50 pF$		4.1 5.6	9.4 10.4	1.0 1.0	10.5 11.5	ns
t _{PZL} , t _{PZH}	Output Enable Time, OE to Q	$V_{CC} = 5.0 \pm 0.5 V$ $C_{L} = 15 pF$ $R_{L} = 1 k \Omega$ $C_{L} = 50 pF$		6.5 7.3	10.2 11.2	1.0 1.0	11.5 12.5	ns
t _{PLZ} , t _{PHZ}	Output Disable Time OE to Q	$\begin{aligned} &V_{CC} = 5.0 \pm 0.5 V & C_L = 50 pF \\ &R_L = 1 k \Omega \end{aligned}$		7.0	11.2	1.0	12.0	ns
toslh, toshl	Output to Output Skew	$V_{CC} = 5.0 \pm 0.5 V$ $C_L = 50 pF$ (Note 1)			1.0		1.0	ns
C _{in}	Maximum Input Capacitance			4	10		10	pF
C _{out}	Maximum 3–State Output Capacitance (Output in High–Impedance State)			9				pF

		Typical @ 25°C, V _{CC} = 5.0V	
C_{PD}	Power Dissipation Capacitance (Note 2)	25	рF

NOISE CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ns}$, $C_L = 50 \text{pF}$, $V_{CC} = 5.0 \text{V}$)

			T _A = 25°C	
Symbol	Parameter	Тур	Max	Unit
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	1.2	1.6	V
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}		-1.6	V
V_{IHD}	V _{IHD} Minimum High Level Dynamic Input Voltage		2.0	V
V _{ILD}	Maximum Low Level Dynamic Input Voltage		0.8	V

TIMING REQUIREMENTS (Input $t_f = t_f = 3.0 \text{ns}$)

			T _A =	25°C	T _A = - 40 to 85°C	
Symbol	Parameter	Test Conditions	Тур	Limit	Limit	Unit
t _w	Minimum Pulse Width, CP	$V_{CC} = 5.0 \pm 0.5 \text{ V}$		6.5	8.5	ns
t _{su}	Minimum Setup Time, D to CP	$V_{CC} = 5.0 \pm 0.5 \text{ V}$		2.5	2.5	ns
t _h	Minimum Hold Time, D to CP	$V_{CC} = 5.0 \pm 0.5 \text{ V}$		2.5	2.5	ns

Parameter guaranteed by design. t_{OSLH} = |t_{PLHm} - t_{PLHn}|, t_{OSHL} = |t_{PHLm} - t_{PHLn}|.
 C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}/8 (per flip-flop). C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74VHCT374ADWRG	SOIC-20WB (Pb-Free)	1000 / Tape & Reel
MC74VHCT374ADTRG	TSSOP-20 (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

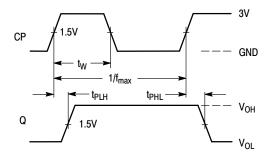


Figure 3. Switching Waveform

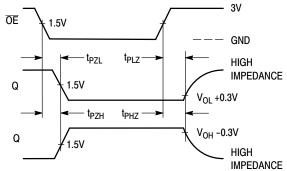


Figure 4. Switching Waveform

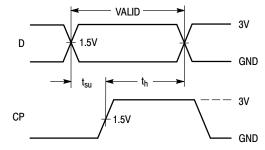
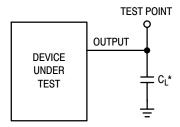
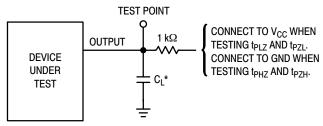


Figure 5. Switching Waveform



*Includes all probe and jig capacitance

Figure 6. Test Circuit



*Includes all probe and jig capacitance

Figure 7. Test Circuit

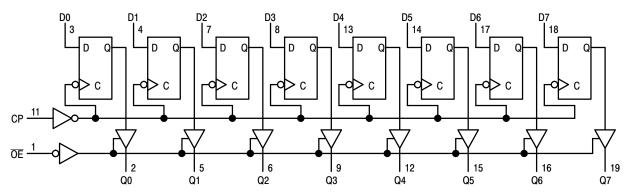
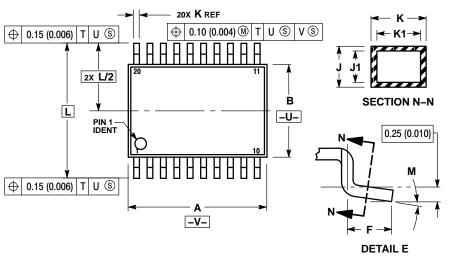
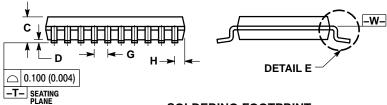


Figure 8. Expanded Logic Diagram

PACKAGE DIMENSIONS

TSSOP-20 CASE 948E-02 **ISSUE C**





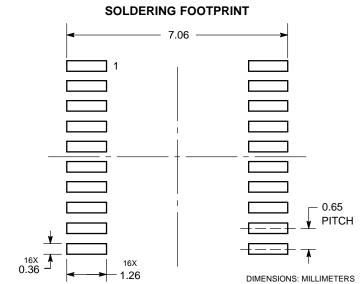
NOTES:

- DTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

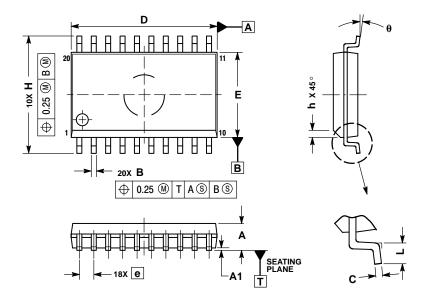
 2. CONTROLLING DIMENSION:
 MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE
 MOLD FLASH, PROTRUSIONS OR GATE
 BURRS. MOLD FLASH OR GATE BURRS
 SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE
 INTER! EAD EI ASH OR PROTRUSION
- INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION
- INTERLEAD FLASH OR PROTRUSION
 SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE
 DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08
 (0.003) TOTAL IN EXCESS OF THE K
 DIMENSION AT MAXIMUM MATERIAL
 CONDITION.
- 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
Н	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40		0.252	BSC
M	0°	8°	0°	8°



PACKAGE DIMENSIONS

SOIC-20 WB **DW SUFFIX** CASE 751D-05 **ISSUE G**



NOTES:

- DIMENSIONS ARE IN MILLIMETERS.
- INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
- PROTRUSION.

 MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

 DIMENSION B DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE PROTRUSION
 SHALL BE 0.13 TOTAL IN EXCESS OF B

 DIMENSION AT MAXIMUM MATERIAL CONDITION

	MILLIMETERS			
DIM	MIN	MAX		
Α	2.35	2.65		
A1	0.10	0.25		
В	0.35	0.49		
C	0.23	0.32		
D	12.65	12.95		
Е	7.40	7.60		
е	1.27	BSC		
Н	10.05	10.55		
h	0.25	0.75		
L	0.50	0.90		
θ	0 °	7 °		

ON Semiconductor and iii) are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all Claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada

Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Flip Flops category:

Click to view products by ON Semiconductor manufacturer:

Other Similar products are found below:

5962-8955201EA MC74HC11ADTG MC10EP29MNG MC74HC11ADTR2G NLV14013BDTR2G NLV14027BDG NLX1G74MUTCG
703557B 746431H 5962-90606022A 5962-9060602FA NLV14013BDR2G M38510/30104BDA M38510/07106BFA M38510/06101B2A NLV74HC74ADR2G TC4013BP(N,F) NLV14013BDG NLV74AC32DR2G NLV74AC74DR2G MC74HC73ADG
CY74FCT16374CTPACT MC74HC11ADR2G 74LVT74D,118 74VHCT9273FT(BJ) MM74HC374WM 74ALVCH162374PAG
TC7WZ74FK,LJ(CT CD54HCT273F HMC853LC3TR HMC723LC3CTR MM74HCT574MTCX MM74HCT273WM SN74LVC74APW
SN74LVC74AD MC74HC73ADTR2G MC74HC11ADG SN74ALVTH16374GR M74HCT273B1R M74HC377RM13TR
M74HC374RM13TR M74HC175B1R M74HC174RM13TR 74ALVTH16374ZQLR 74ALVTH32374ZKER 74AUP1G74DC,125
74VHC374FT(BJ) 74VHC9273FT(BJ) NLV14013BCPG